

# GP-25 石墨基板 Graphite Circuit Board



Application 產品應用端：  
LED、M/B、LCD-TV、Notebook、  
PC and other applications.

Property	Range	Unit
Peel strength 銅片與石墨之附著力	2.5	Kg/cm
Thickness 厚度	1.2	Mm
Breakdown Voltage 擊潰電壓	2.4	KV
Solder Heat Resistance 焊接耐熱溫度	230 (180s)	°C
Heat Shorting 熱衝擊(全環境包裹溫度)	300(80s)	°C
Thermal conductivity 導熱係數	X	400
	Y	400
	Z	15
Thermal Resistance 熱阻抗	1.5	°C in <sup>2</sup> /W
Heat Proliferate 熱擴散率	3.0	cm <sup>2</sup> /s
Specific Gravity 比重	1.3	-
Graphite Contained 石墨含量	99.5	%
Density 密度	1.5	g/cm <sup>3</sup>

## 特性Character

1. x,y,z 三軸向擁有高導熱係數。

Ultra high thermal conductivity in x,y,z axis.

2. 熱傳導效能優於市面上所有的鋁或銅基板。

The thermal conductivity of graphite board is better than aluminum circuit board or cooper circuit board.

3. 熱阻低於市面上所有鋁或銅基板。

The thermal resistance of graphite board is lower than aluminum circuit board or copper circuit board.

4. 材質輕。

Light weight.

5. 屬於中低價位之高效能基板。

Low cost.

6. 延長LED壽命。

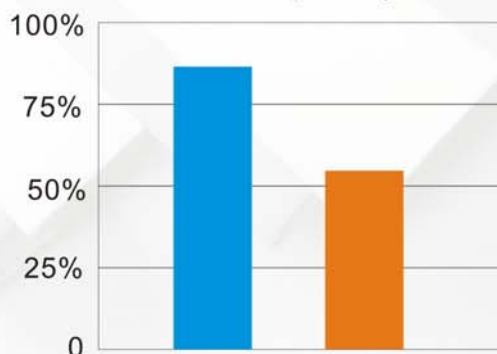
Long Life usage.

7. 減少散熱器之散熱面積設計。

Reduce the area of heat dissipation not the heat spreader when designed.

導熱效能比較表

Thermal Conductivity comparison sheet



石墨基板 一般鋁基板

Graphite Circuit Board Aluminum Circuit Board